CM1637



4, 6 and 8 Channel EMI Filter Arrays with ESD Protection

Features

- Four, six and eight channels of EMI filtering with ESD protection
- Pi-style EMI filters in a capacitor-resistor-capacitor (C-R-C) network
- ±15kV ESD protection (IEC 61000-4-2, contact discharge)
- ±30kV ESD protection (HBM)
- Greater than 25dB of attenuation from 800MHz to 3GHz
- UDFN package with 0.40mm lead pitch:
 - 4-ch. = 8-lead UDFN
 - 6-ch. = 12-lead UDFN
 - 8-ch. = 16-lead UDFN
- Tiny UDFN package size:
 - 8-lead: 1.7mm x 1.35mm x 0.5mm
 - 12-lead: 2.5mm x 1.35mm x 0.5mm
 - 16-lead: 3.3mm x 1.35mm x 0.5mm
- Increased robustness against vertical impacts during manufacturing process
- Lead-free finishing

Applications

- I/O port protection for mobile handsets, notebook computers, PDAs etc.
- EMI filtering for data ports in cell phones, PDAs or notebook computers.
- EMI filtering for LCD, camera and chip-to-chip data lines

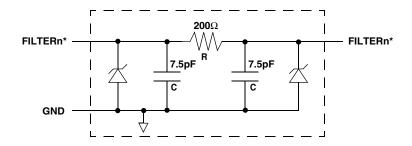
Product Description

California Micro Devices's CM1637 is an EMI filter array with ESD protection, which integrates either four, six or eight pi filters (C-R-C). Each CM1637 filter has component values of 7.5pF-200Ω-7.5pF. These parts include ESD protection diodes on every pin, providing a very high level of protection for sensitive electronic components that may be subjected to electrostatic discharge (ESD). The ESD diodes connected to the filter ports safely dissipate ESD strikes of ±15kV contact discharge, twice the specification requirement of the IEC 61000-4-2, Level 4 international standard. Using the MIL-STD-883 (Method 3015) specification for Human Body Model (HBM) ESD, the pins are protected for contact discharges at greater than ±30kV.

This device is particularly well-suited for portable electronics (e.g. mobile handsets, PDAs, notebook computers) because of its small package and easy-to-use pin assignments. In particular, the CM1637 is ideal for EMI filtering and protecting data lines from ESD in wireless handsets.

The CM1637 is available in space-saving, ultra-lowprofile, 8-lead, 12-lead and 16-lead 0.4mm pitch UDFN packages. It is fabricated with California Micro Devices' Centurion™ process and available with lead-free finishing. This new small UDFN package provides up to 42% board space savings vs. the 0.50mm pitch UDFN packages.

Electrical Schematic

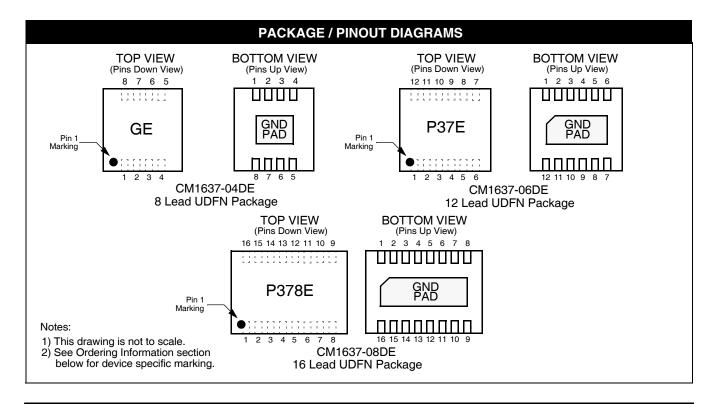


1 of 4/6/8 EMI Filtering + ESD Channels

* See Package/Pinout Diagram for expanded pin information.



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PIN DESCRIPTIONS									
Pins					Pins				
1637- 04Dx	1637- 06Dx	1637- 08Dx	NAME	DESCRIPTION	1637- 04Dx	1637- 06Dx	1637- 08Dx	NAME	DESCRIPTION
1	1	1	FILTER1	Filter Channel 1	8	12	16	FILTER1	Filter Channel 1
2	2	2	FILTER2	Filter Channel 2	7	11	15	FILTER2	Filter Channel 2
3	3	3	FILTER3	Filter Channel 3	6	10	14	FILTER3	Filter Channel 3
4	4	4	FILTER4	Filter Channel 4	5	9	13	FILTER4	Filter Channel 4
	5	5	FILTER5	Filter Channel 5		8	12	FILTER5	Filter Channel 5
	6	6	FILTER6	Filter Channel 6		7	11	FILTER6	Filter Channel 6
		7	FILTER7	Filter Channel 7			10	FILTER7	Filter Channel 7
		8	FILTER8	Filter Channel 8			9	FILTER8	Filter Channel 8
	GND Pad		GND	Device Ground					

Ordering Information

PART NUMBERING INFORMATION							
	Lead-free Finish						
Leads/Pins	Package	Ordering Part Number ¹	Part Marking				
8	UDFN-08	CM1637-04DE	GE				
12	UDFN-12	CM1637-06DE	P37E				
16	UDFN-16	CM1637-08DE	P378E				

Note 1: Parts are shipped in Tape & Reel form unless otherwise specified.

CM1637



Specifications

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	RATING	UNITS					
Storage Temperature Range	-65 to +150	°C					
DC Power per Resistor	100	mW					
Package DC Power Rating	300	mW					

STANDARD OPERATING CONDITIONS							
PARAMETER	RATING	UNITS					
Operating Temperature Range	-40 to +85	°C					

ELECTRICAL OPERATING CHARACTERISTICS (SEE NOTE 1)								
SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS		
R	Resistance		160	200	240	Ω		
C _{TOTAL}	Total Channel Capacitance	At 2.5VDC Reverse Bias, 1MHz, 30mVAC	12	15	18	pF		
С	Capacitance	At 2.5V DC, 1MHz, 30mV AC	6	7.5	9	pF		
V _{DIODE}	Diode Standoff Voltage	I _{DIODE} = 10μA		6.0		V		
I _{LEAK}	Diode Leakage Current (reverse bias)	V _{DIODE} = 3.3V		0.1	1	μА		
V _{SIG}	Signal Voltage Positive Clamp Negative Clamp	I _{LOAD} = 10mA I _{LOAD} = -10mA	5.6 -0.4	6.8 -0.8		V V		
V _{ESD}	In-system ESD Withstand Voltage a) Human Body Model, MIL-STD- 883, Method 3015 b) Contact Discharge per IEC 61000-4-2 Level 4	Notes 2 and 3	±30 ±15			kV kV		
f _C	Cut-off Frequency Z_{SOURCE} =50 Ω , Z_{LOAD} =50 Ω	R = 200Ω, C = 15pF; Note 3		210		MHz		
A _{1GHz}	Absolute Attenuation @ 1GHz from 0dB Level	$Z_{SOURCE} = 50\Omega$, $Z_{LOAD} = 50\Omega$, DC Bias = 0V; Notes 1, 4 and 5		32		dB		
A _{800MHz} - 6GHz	Absolute Attenuation @ 800MHz to 6GHz from 0dB Level	$Z_{\text{SOURCE}} = 50\Omega$, $Z_{\text{LOAD}} = 50\Omega$, DC Bias = 0V; Notes 1, 4 and 5		27		dB		

Note 1: $T_A=25$ °C unless otherwise specified.

Note 2: ESD applied to input and output pins with respect to GND, one at a time.

Note 3: These parameters are guaranteed by design and characterization.

Note 4: Attenuation / RF curves characterized by a network analyzer using microprobes.

Note 5: These parameters are NOT guaranteed by design, characterization and production.



Performance Information

Typical Filter Performance (T_A=25°C, DC Bias=0V, 50 Ohm Environment)

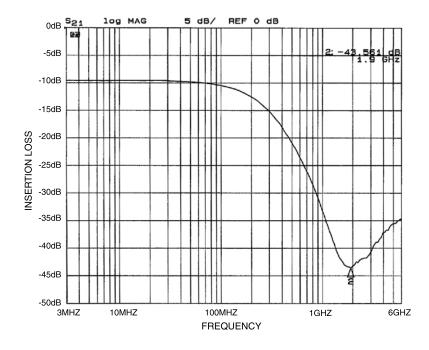


Figure 1. Insertion Loss vs. Frequency (FILTER1 Input to GND, CM1637-04DE)

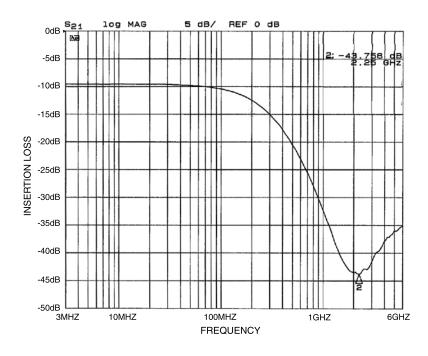


Figure 2. Insertion Loss vs. Frequency (FILTER2 Input to GND, CM1637-04DE)



Typical Filter Performance (T_A=25°C, DC Bias=0V, 50 Ohm Environment)

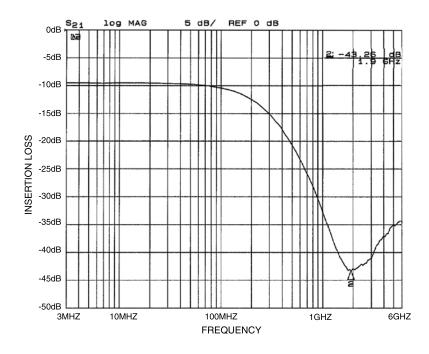


Figure 3. Insertion Loss vs. Frequency (FILTER3 Input to GND, CM1637-04DE)

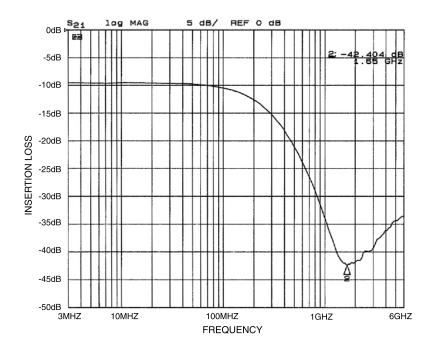


Figure 4. Insertion Loss vs. Frequency (FILTER4 Input to GND, CM1637-04DE)



Typical Filter Performance (T_A=25°C, DC Bias=0V, 50 Ohm Environment)

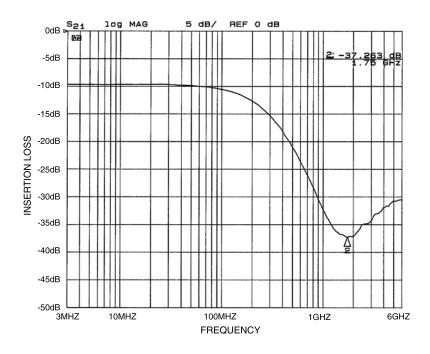


Figure 5. Insertion Loss vs. Frequency (FILTER1 Input to GND, CM1637-06DE)

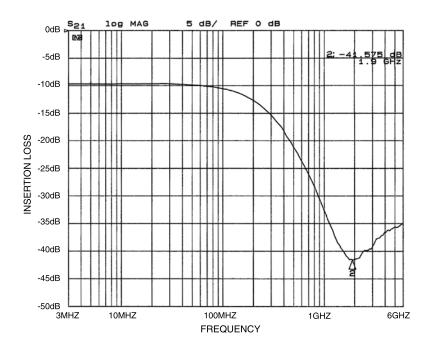


Figure 6. Insertion Loss vs. Frequency (FILTER2 Input to GND, CM1637-06DE)



Typical Filter Performance (T_A=25°C, DC Bias=0V, 50 Ohm Environment)

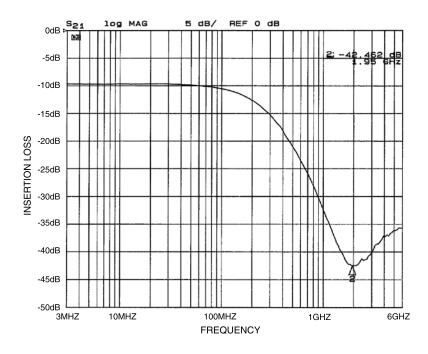


Figure 7. Insertion Loss vs. Frequency (FILTER3 Input to GND, CM1637-06DE)

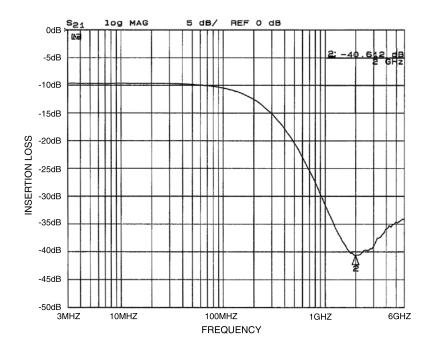


Figure 8. Insertion Loss vs. Frequency (FILTER4 Input to GND, CM1637-06DE)



Typical Filter Performance (T_A=25°C, DC Bias=0V, 50 Ohm Environment)

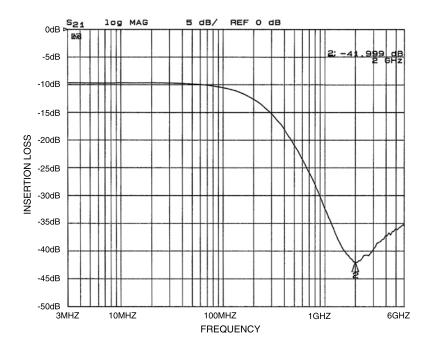


Figure 9. Insertion Loss vs. Frequency (FILTER5 Input to GND, CM1637-06DE)

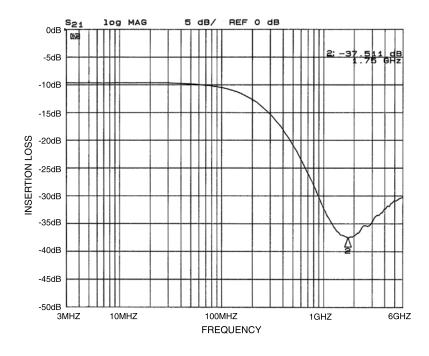


Figure 10. Insertion Loss vs. Frequency (FILTER6 Input to GND, CM1637-06DE)



Typical Filter Performance (T_A=25°C, DC Bias=0V, 50 Ohm Environment)

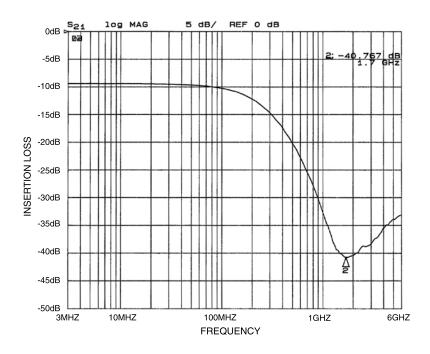


Figure 11. Insertion Loss vs. Frequency (FILTER1 Input to GND, CM1637-08DE)

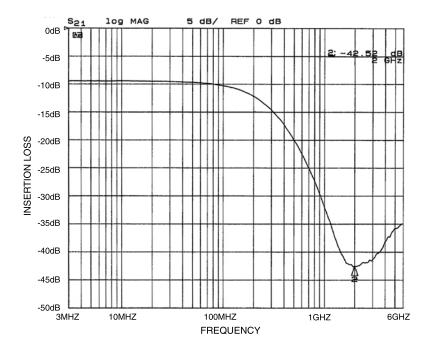


Figure 12. Insertion Loss vs. Frequency (FILTER2 Input to GND, CM1637-08DE)

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Typical Filter Performance (T_A=25°C, DC Bias=0V, 50 Ohm Environment)

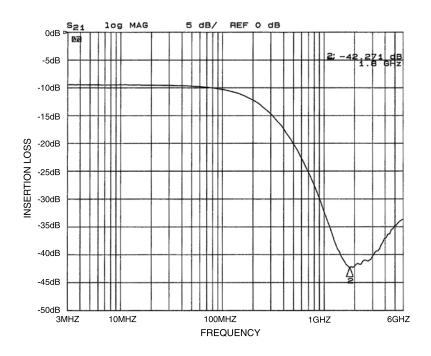


Figure 13. Insertion Loss vs. Frequency (FILTER3 Input to GND, CM1637-08DE)

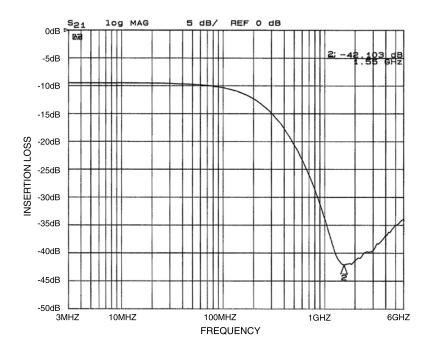


Figure 14. Insertion Loss vs. Frequency (FILTER4 Input to GND, CM1637-08DE)



Typical Filter Performance (T_A=25°C, DC Bias=0V, 50 Ohm Environment)

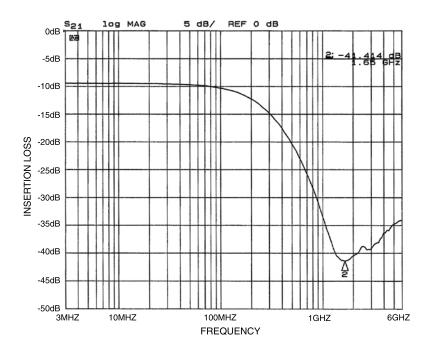


Figure 15. Insertion Loss vs. Frequency (FILTER5 Input to GND, CM1637-08DE)

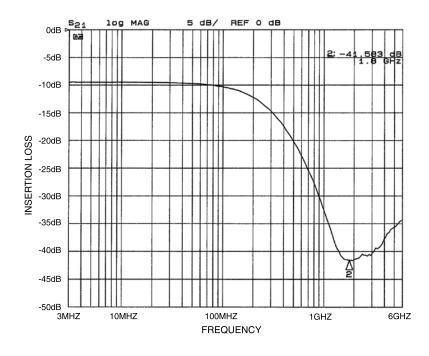


Figure 16. Insertion Loss vs. Frequency (FILTER6 Input to GND, CM1637-08DE)



Typical Filter Performance (T_A=25°C, DC Bias=0V, 50 Ohm Environment)

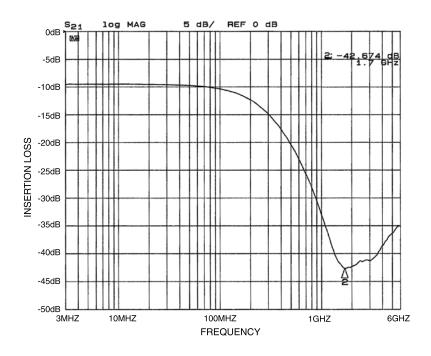


Figure 17. Insertion Loss vs. Frequency (FILTER7 Input to GND, CM1637-08DE)

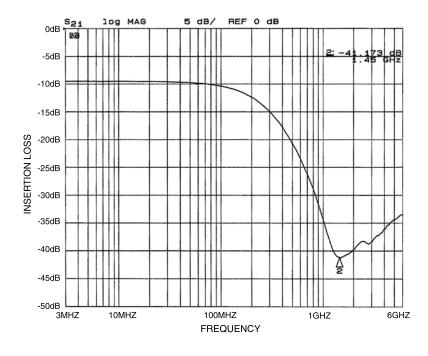


Figure 18. Insertion Loss vs. Frequency (FILTER8 Input to GND, CM1637-08DE)



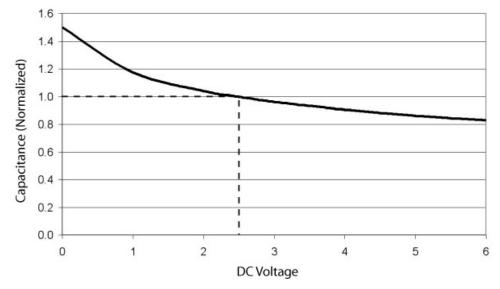


Figure 19. Filter Capacitance vs. Input Voltage over Temperature (normalized to capacitance at 2.5VDC and 25°C)



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Mechanical Details

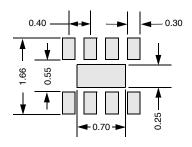
UDFN-08 Mechanical Specifications

Dimensions for the CM1637 supplied in a 8-lead, 0.4mm pitch UDFN package are presented below.

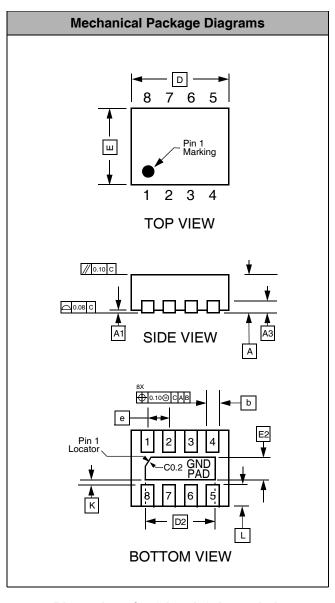
	PAC	KAGE	DIME	NSIO	NS		
Package		UDFN					
JEDEC No.	MO-229C [†]						
Leads				8			
Dim.	N	lillimete	rs		Inches		
Dilli.	Min	Nom	Max	Min	Nom	Max	
Α	0.45	0.50	0.55	0.018	0.020	0.022	
A1	0.00	0.02	0.05	0.000	0.001	0.002	
А3	C).127 RE	F	0	0.005 RE	F	
b	0.15	0.20	0.25	0.006	0.008	0.010	
D	1.60	1.70	1.80	0.063	0.067	0.071	
D2	1.10	1.20	1.30	0.043	0.047	0.051	
E	1.25	1.35	1.45	0.049	0.053	0.057	
E2	0.30	0.40	0.50	0.012	0.016	0.020	
е	(0.40 BS	С	0	0.016 BS	С	
K	0.20			0.008			
L	0.15	0.25	0.35	0.006	0.010	0.014	
# per tape and reel	3000 pieces						
Controlling dimension: millimeters							

[†]This package is compliant with JEDEC standard MO-229C with the exception of the "D", "D2", "E", "E2", "K" and "L" dimensions as called out in the table above.

Recommend PCB Land Pattern



Note: Dimensions in millimeters. Drawing not to scale.



Dimensions for 8-Lead, 0.4mm pitch **UDFN** package



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Mechanical Details (cont'd)

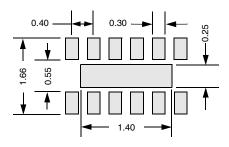
UDFN-12 Mechanical Specifications

Dimensions for the CM1637 suplied in a 12-lead, 0.4mm pitch UDFN package are presented below.

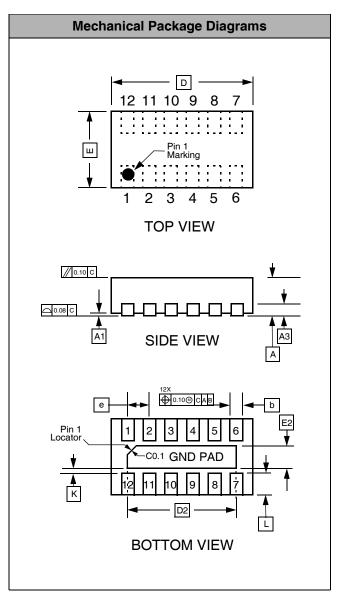
	PAC	KAGE	DIME	NSIO	NS			
Package		UDFN						
JEDEC No.	MO-229C [†]							
Leads			1	12				
Dim.	N	lillimete	rs		Inches			
Dilli.	Min	Nom	Max	Min	Nom	Max		
Α	0.45	0.50	0.55	0.018	0.020	0.022		
A1	0.00	0.02	0.05	0.000	0.001	0.002		
А3	C).127 RE	F	O	.005 RE	F		
b	0.15	0.20	0.25	0.006	0.008	0.010		
D	2.40	2.50	2.60	0.094	0.098	0.102		
D2	1.90	2.00	2.10	0.075	0.079	0.083		
E	1.25	1.35	1.45	0.049	0.053	0.057		
E2	0.30	0.40	0.50	0.012	0.016	0.020		
е		0.40 BS	С	0	.016 BS	С		
K	0.20			0.008				
L	0.15	0.25	0.35	0.006	0.010	0.014		
# per tape and reel	3000 pieces							
	Controlling dimension: millimeters							

[†]This package is compliant with JEDEC standard MO-229C with the exception of the "D", "D2", "E", "E2", "K" and "L" dimensions as called out in the table above.

Recommend PCB Land Pattern



Note: Dimensions in millimeters. Drawing not to scale.



Dimensions for 12-Lead, 0.4mm pitch **UDFN** package

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Mechanical Details (cont'd)

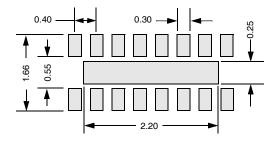
UDFN-16 Mechanical Specifications

Dimensions for the CM1637 supplied in a 16-lead, 0.4mm pitch UDFN package are presented below.

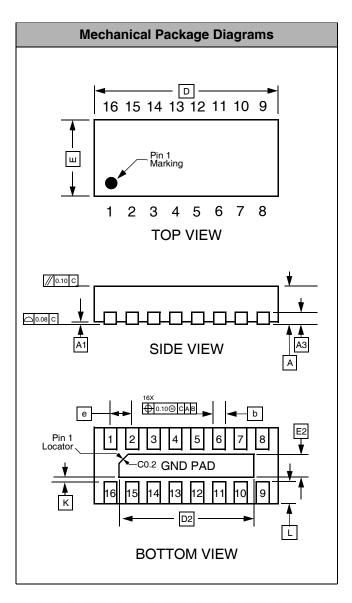
	PAC	KAGE	DIME	NSIO	NS		
Package	UDFN						
JEDEC No.	MO-229C [†]						
Leads			1	16			
Dim.	N	lillimete	rs		Inches		
Dilli.	Min	Nom	Max	Min	Nom	Max	
Α	0.45	0.50	0.55	0.018	0.020	0.022	
A1	0.00	0.02	0.05	0.000	0.001	0.002	
А3	0.127 REF 0.005 REF				F		
b	0.15	0.20	0.25	0.006	0.008	0.010	
D	3.20	3.30	3.40	0.126	0.130	0.134	
D2	2.70	2.80	2.90	0.106	0.110	0.114	
E	1.25	1.35	1.45	0.049	0.053	0.057	
E2	0.30	0.40	0.50	0.012	0.016	0.020	
е		0.40 BS	С	C	.016 BS	С	
K	0.20			0.008			
L	0.15	0.25	0.35	0.006	0.010	0.014	
# per tape and reel	3000 pieces						
	Controlling dimension: millimeters						

[†]This package is compliant with JEDEC standard MO-229C with the exception of the "D", "D2", "E", "E2", "K" and "L" dimensions as called out in the table above.

Recommend PCB Land Pattern



Note: Dimensions in millimeters. Drawing not to scale.



Dimensions for 16-Lead, 0.4mm pitch **UDFN** package

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